

AMP | AMP TC-ZIF

TE Internal #: 6565204-1

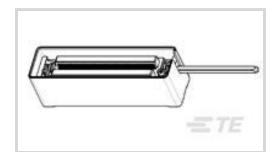
Vertical, Wire-to-Board, 260 Position, .8 mm [.031 in] Centerline, Gold, Through Hole - Solder, Signal, Black / Natural, Tray, AMP TC-

ZIF

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Connectors > PCB Connectors > PCB Headers & Receptacles



Connector & Contact Terminates To: Printed Circuit Board

Contact Current Rating (Max): .5 A

Number of Positions: 260

Connector System: Wire-to-Board
Centerline (Pitch): .8 mm [.031 in]

Features

Product Type Features

Connector Shape	Rectangular
Connector & Contact Terminates To	Printed Circuit Board
Connector System	Wire-to-Board
Sealable	No

Configuration Features

Number of Power Positions	0
Number of Signal Positions	260
Number of Positions	260
Number of Rows	4
PCB Mount Orientation	Vertical

Electrical Characteristics

Body Features

Connector & Keying Code	Y
Primary Product Color	Black, Natural

Contact Features

Contact Layout	Inline
Contact Underplating Material	Nickel



PCB Contact Termination Area Plating Material	Gold
Contact Current Rating (Max)	.5 A
Contact Mating Area Plating Material	Gold
Contact Type	Tab
Termination Features	
Termination Method to PCB	Through Holo Colder
	Through Hole - Solder
Mechanical Attachment	
PCB Mount Alignment Type	Standard Polarized Tail
Mating Alignment Type	Keyed
Panel Mount Feature Type	Mounting Hole
PCB Mount Retention Type	Mounting Hole
Mating Retention Type	Locking Latch
Mating Retention	With
Mating Alignment	With
PCB Mount Alignment	Without
PCB Mount Retention	With
Housing Features	
Housing Material	Die Cast Zinc
Centerline (Pitch)	.8 mm[.031 in]
Dimensions	
PCB Thickness (Recommended)	1.6 – 2. mm[.063 – .079 in]
Usage Conditions	
Operating Temperature Range	-55 – 85 °C[-67 – 185 °F]
Operation/Application	
Shielded	Yes
Circuit Application	Signal
Industry Standards	
Glow Wire Rating	Standard Part - Not Glow Wire
UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Quantity	30
Packaging Method	Tray



Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2024 (241) Candidate List Declared Against: JUNE 2024 (241) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Wave solder capable to 260°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts





Also in the Series | AMP TC-ZIF





Customers Also Bought



















Documents

Product Drawings

TC-ZIF REC ASSY 260P

Japanese

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_6565204-1_L.2d_dxf.zip

Vertical, Wire-to-Board, 260 Position, .8 mm [.031 in] Centerline, Gold, Through Hole - Solder, Signal, Black / Natural, Tray, AMP TC-ZIF



English

Customer View Model

ENG_CVM_CVM_6565204-1_L.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_6565204-1_L.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Product Specifications

Application Specification

Japanese